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Aluminium Alloys: Microstructure, Properties, Heat Treatment, **Forming and Welding**

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Message from the Guest Editors

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Deadline for manuscript

closed (30 September 2023)

submissions:











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Message from the Editorial Board

Metallic materials play a vital role in the economic life of modern societies; contributions are sought on fresh developments that enhance our understanding of the fundamental aspects related to the relationships between processing, properties and microstructure - disciplines in metallurgical field the ranging from processing. and mechanical behavior. phase transitions microstructural evolution, nanostructures, as well as unique metallic properties – inspire general and scholarly interest among the scientific community.

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(Metals and Alloys)

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